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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

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Details

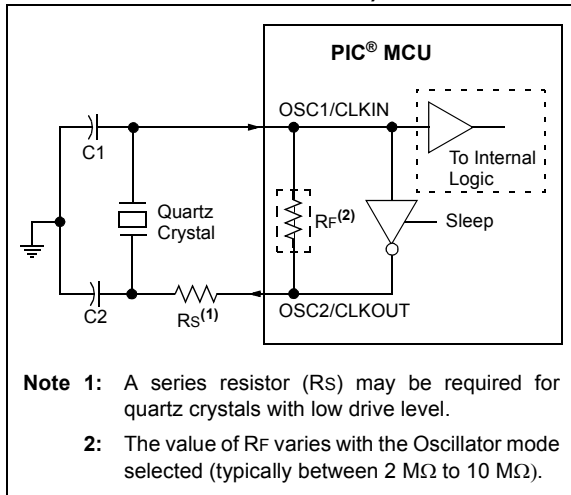
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I ² C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	5
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	8-VDFN Exposed Pad
Supplier Device Package	8-DFN (3x3)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lf1840t-i-mf

PIC12(L)F1840

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FIGURE 5-3: QUARTZ CRYSTAL OPERATION (LP, XT OR HS MODE)

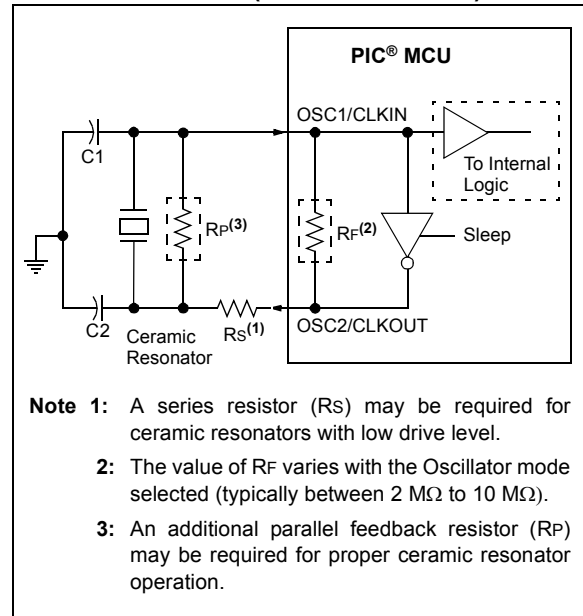


Note 1: Quartz crystal characteristics vary according to type, package and manufacturer. The user should consult the manufacturer data sheets for specifications and recommended application.

- 2:** Always verify oscillator performance over the V_{DD} and temperature range that is expected for the application.
- 3:** For oscillator design assistance, reference the following Microchip Applications Notes:

- AN826, "Crystal Oscillator Basics and Crystal Selection for *rPIC*[®] and *PIC*[®] Devices" (DS00826)
- AN849, "Basic *PIC*[®] Oscillator Design" (DS00849)
- AN943, "Practical *PIC*[®] Oscillator Analysis and Design" (DS00943)
- AN949, "Making Your Oscillator Work" (DS00949)

FIGURE 5-4: CERAMIC RESONATOR OPERATION (XT OR HS MODE)



5.2.1.3 Oscillator Start-up Timer (OST)

If the oscillator module is configured for LP, XT or HS modes, the Oscillator Start-up Timer (OST) counts 1024 oscillations from OSC1. This occurs following a Power-on Reset (POR) and when the Power-up Timer (PWRT) has expired (if configured), or a wake-up from Sleep. During this time, the program counter does not increment and program execution is suspended, unless either FSCM or Two-Speed Start-Up are enabled. In this case, code will continue to execute at the selected INTOSC frequency while the OST is counting. The OST ensures that the oscillator circuit, using a quartz crystal resonator or ceramic resonator, has started and is providing a stable system clock to the oscillator module.

In order to minimize latency between external oscillator start-up and code execution, the Two-Speed Clock Start-up mode can be selected (see **Section 5.4 "Two-Speed Clock Start-up Mode"**).

7.0 RESETS

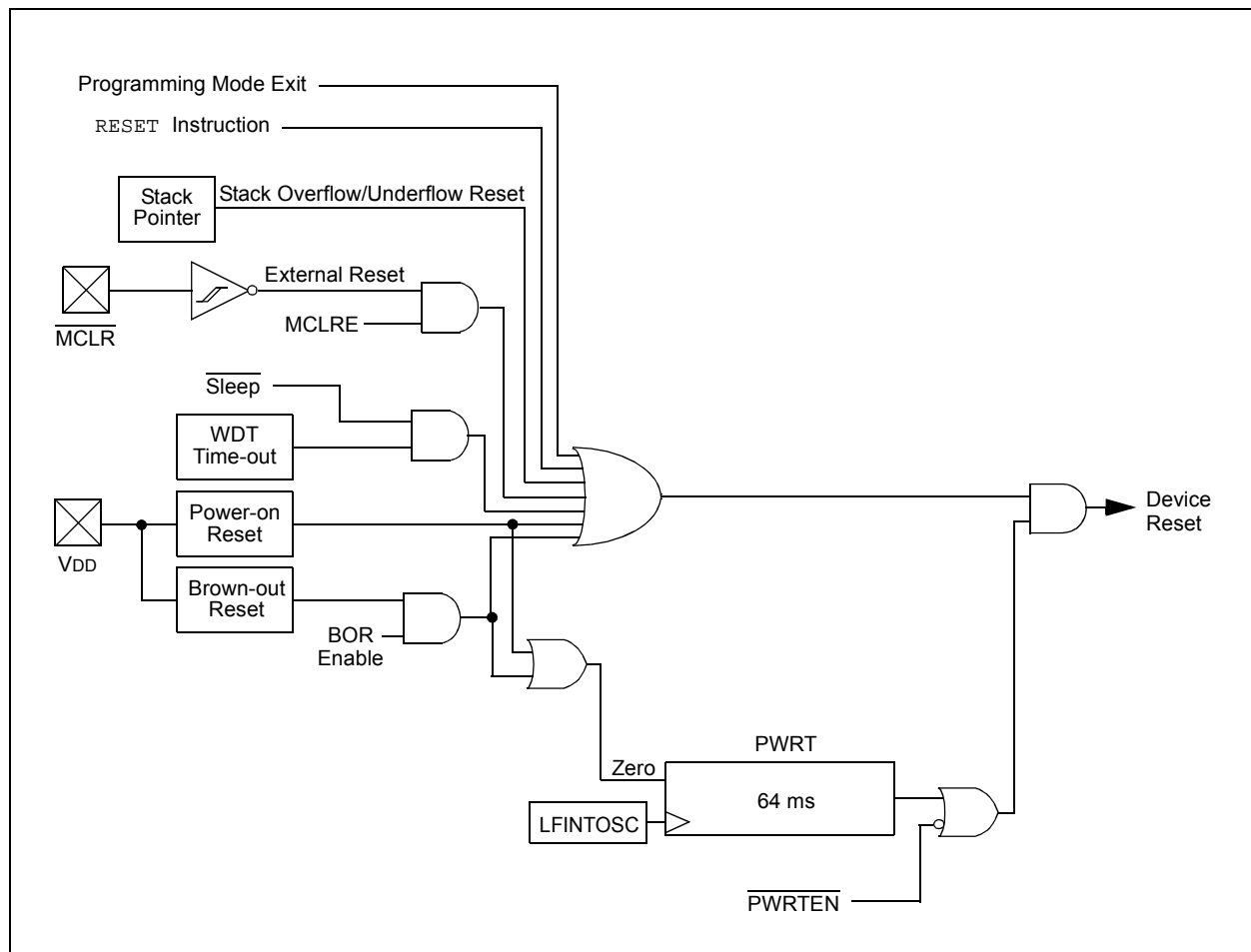
There are multiple ways to reset this device:

- Power-On Reset (POR)
- Brown-Out Reset (BOR)
- MCLR Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional power-up timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 7-1.

FIGURE 7-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



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TABLE 7-5: SUMMARY OF REGISTERS ASSOCIATED WITH RESETS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BORCON	SBOREN	BORFS	—	—	—	—	—	BORRDY	61
PCON	STKOVF	STKUNF	—	—	RMCLR	RI	POR	BOR	65
STATUS	—	—	—	TO	PD	Z	DC	C	15
WDTCON	—	—	WDTPS<4:0>					SWDTEN	83

Legend: — = unimplemented, read as '0'. Shaded cells are not used by Resets.

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REGISTER 8-5: PIR2: PERIPHERAL INTERRUPT REQUEST REGISTER 2

R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0
OSFIF	—	C1IF	EEIF	BCL1IF	—	—	—
bit 7							bit 0

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

u = Bit is unchanged

x = Bit is unknown

-n/n = Value at POR and BOR/Value at all other Resets

'1' = Bit is set

'0' = Bit is cleared

- bit 7 **OSFIF:** Oscillator Fail Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending
- bit 6 **Unimplemented:** Read as '0'
- bit 5 **C1IF:** Comparator C1 Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending
- bit 4 **EEIF:** EEPROM Write Completion Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending
- bit 3 **BCL1IF:** MSSP Bus Collision Interrupt Flag bit
1 = Interrupt is pending
0 = Interrupt is not pending
- bit 2-0 **Unimplemented:** Read as '0'

Note: Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the Global Enable bit, GIE, of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

TABLE 8-1: SUMMARY OF REGISTERS ASSOCIATED WITH INTERRUPTS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCFIE	TMR0IF	INTF	IOCFIF	72
OPTION_REG	WPUEN	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			145
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	73
PIE2	OSFIE	—	C1IE	EEIE	BCL1IE	—	—	—	74
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	75
PIR2	OSFIF	—	C1IF	EEIF	BCL1IF	—	—	—	76

Legend: — = unimplemented locations read as '0'. Shaded cells are not used by Interrupts.

9.2 Low-Power Sleep Mode

The PIC12F1840 device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. The PIC12F1840 allows the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

9.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

9.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The LDO will remain in the normal power mode when those peripherals are enabled. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-Out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)
- Comparator
- ECCP (Capture mode)

Note: The PIC12LF1840 does not have a configurable Low-Power Sleep mode. PIC12LF1840 is an unregulated device and is always in the lowest power state when in Sleep, with no wake-up time penalty. This device has a lower maximum V_{DD} and I/O voltage than the PIC12F1840. See **Section 30.0 “Electrical Specifications”** for more information.

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20.1.3 SOFTWARE PROGRAMMABLE PRESCALER

A software programmable prescaler is available for exclusive use with Timer0. The prescaler is enabled by clearing the PSA bit of the OPTION_REG register.

Note: The Watchdog Timer (WDT) uses its own independent prescaler.

There are eight prescaler options for the Timer0 module ranging from 1:2 to 1:256. The prescale values are selectable via the PS<2:0> bits of the OPTION_REG register. In order to have a 1:1 prescaler value for the Timer0 module, the prescaler must be disabled by setting the PSA bit of the OPTION_REG register.

The prescaler is not readable or writable. All instructions writing to the TMR0 register will clear the prescaler.

20.1.4 TIMER0 INTERRUPT

Timer0 will generate an interrupt when the TMR0 register overflows from FFh to 00h. The TMR0IF interrupt flag bit of the INTCON register is set every time the TMR0 register overflows, regardless of whether or not the Timer0 interrupt is enabled. The TMR0IF bit can only be cleared in software. The Timer0 interrupt enable is the TMR0IE bit of the INTCON register.

Note: The Timer0 interrupt cannot wake the processor from Sleep since the timer is frozen during Sleep.

20.1.5 8-BIT COUNTER MODE SYNCHRONIZATION

When in 8-Bit Counter mode, the incrementing edge on the T0CKI pin must be synchronized to the instruction clock. Synchronization can be accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the instruction clock. The high and low periods of the external clocking source must meet the timing requirements as shown in **Section 30.0 “Electrical Specifications”**.

20.1.6 OPERATION DURING SLEEP

Timer0 cannot operate while the processor is in Sleep mode. The contents of the TMR0 register will remain unchanged while the processor is in Sleep mode.

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REGISTER 23-4: MDCARL: MODULATION LOW CARRIER CONTROL REGISTER

R/W-x/u	R/W-x/u	R/W-x/u	U-0	R/W-x/u	R/W-x/u	R/W-x/u	R/W-x/u
MDCLODIS	MDCLPOL	MDCLSYNC	—	MDCL<3:0>			
bit 7							bit 0

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
u = Bit is unchanged x = Bit is unknown -n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set '0' = Bit is cleared

- bit 7 **MDCLODIS:** Modulator Low Carrier Output Disable bit
1 = Output signal driving the peripheral output pin (selected by MDCL<3:0> of the MDCARL register) is disabled
0 = Output signal driving the peripheral output pin (selected by MDCL<3:0> of the MDCARL register) is enabled
- bit 6 **MDCLPOL:** Modulator Low Carrier Polarity Select bit
1 = Selected low carrier signal is inverted
0 = Selected low carrier signal is not inverted
- bit 5 **MDCLSYNC:** Modulator Low Carrier Synchronization Enable bit
1 = Modulator waits for a falling edge on the low time carrier signal before allowing a switch to the high time carrier
0 = Modulator Output is not synchronized to the low time carrier signal⁽¹⁾
- bit 4 **Unimplemented:** Read as '0'
- bit 3-0 **MDCL<3:0>** Modulator Data High Carrier Selection bits ⁽¹⁾
1111 = Reserved. No channel connected.
•
•
•
0101 = Reserved. No channel connected.
0100 = CCP1 output (PWM Output mode only)
0011 = Reference Clock module signal
0010 = Reserved. No channel connected.
0001 = MDCIN1 port pin
0000 = Vss

Note 1: Narrowed carrier pulse widths or spurs may occur in the signal stream if the carrier is not synchronized.

TABLE 23-1: SUMMARY OF REGISTERS ASSOCIATED WITH DATA SIGNAL MODULATOR MODE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
MDCARH	MDCHODIS	MDCHPOL	MDCHSYNC	—	MDCH<3:0>				169
MDCARL	MDCLODIS	MDCLPOL	MDCLSYNC	—	MDCL<3:0>				170
MDCON	MDEN	MDOE	MDSLRL	MDOPOL	MDOUT	—	—	MDBIT	167
MDSRC	MDMSODIS	—	—	—	MDMS<3:0>				168

Legend: — = unimplemented, read as '0'. Shaded cells are not used in the Data Signal Modulator mode.

24.4.4 PROGRAMMABLE DEAD-BAND DELAY MODE

In half-bridge applications where all power switches are modulated at the PWM frequency, the power switches normally require more time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches may be on for a short period of time until one switch completely turns off. During this brief interval, a very high current (*shoot-through current*) will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on either of the power switches is normally delayed to allow the other switch to completely turn off.

In Half-Bridge mode, a digitally programmable dead-band delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See Figure 24-12 for illustration. The lower seven bits of the associated PWM1CON register (Register 24-3) sets the delay period in terms of microcontroller instruction cycles (T_{CY} or $4 T_{OSC}$).

FIGURE 24-12: EXAMPLE OF HALF-BRIDGE PWM OUTPUT

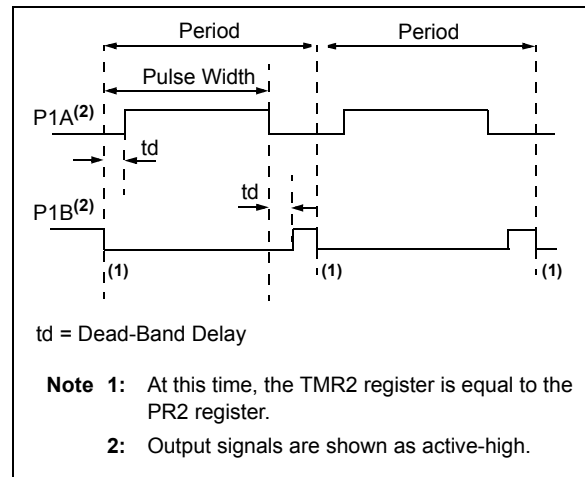
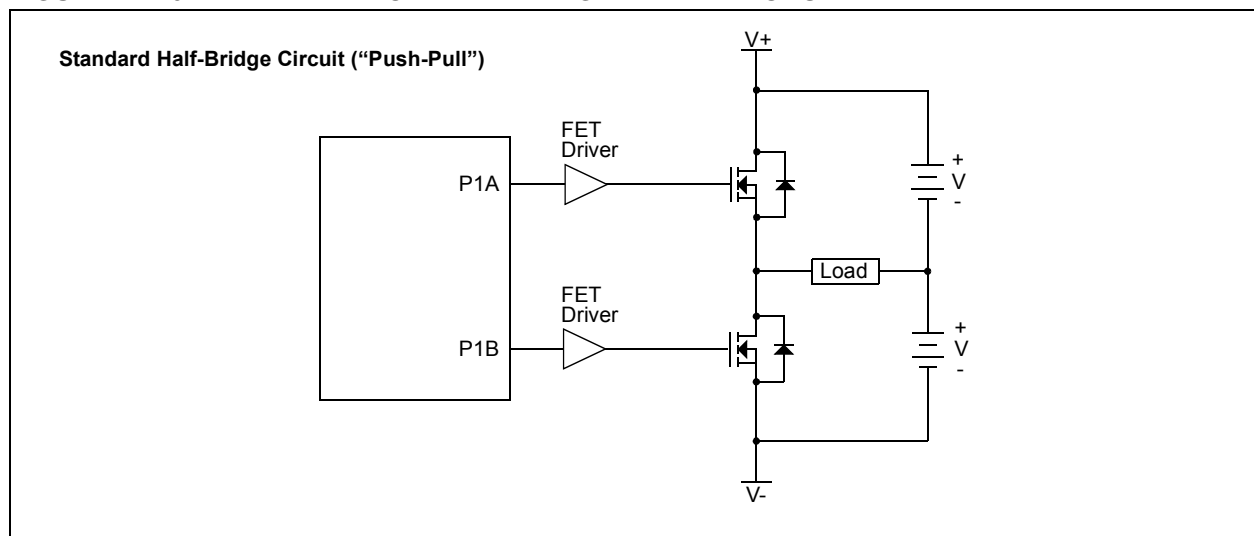


FIGURE 24-13: EXAMPLE OF HALF-BRIDGE APPLICATIONS



When one device is transmitting a logical one, or letting the line float, and a second device is transmitting a logical zero, or holding the line low, the first device can detect that the line is not a logical one. This detection, when used on the SCL line, is called clock stretching. Clock stretching gives slave devices a mechanism to control the flow of data. When this detection is used on the SDA line, it is called arbitration. Arbitration ensures that there is only one master device communicating at any single time.

25.3.1 CLOCK STRETCHING

When a slave device has not completed processing data, it can delay the transfer of more data through the process of clock stretching. An addressed slave device may hold the SCL clock line low after receiving or sending a bit, indicating that it is not yet ready to continue. The master that is communicating with the slave will attempt to raise the SCL line in order to transfer the next bit, but will detect that the clock line has not yet been released. Because the SCL connection is open-drain, the slave has the ability to hold that line low until it is ready to continue communicating.

Clock stretching allows receivers that cannot keep up with a transmitter to control the flow of incoming data.

25.3.2 ARBITRATION

Each master device must monitor the bus for Start and Stop bits. If the device detects that the bus is busy, it cannot begin a new message until the bus returns to an Idle state.

However, two master devices may try to initiate a transmission on or about the same time. When this occurs, the process of arbitration begins. Each transmitter checks the level of the SDA data line and compares it to the level that it expects to find. The first transmitter to observe that the two levels do not match, loses arbitration, and must stop transmitting on the SDA line.

For example, if one transmitter holds the SDA line to a logical one (lets it float) and a second transmitter holds it to a logical zero (pulls it low), the result is that the SDA line will be low. The first transmitter then observes that the level of the line is different than expected and concludes that another transmitter is communicating.

The first transmitter to notice this difference is the one that loses arbitration and must stop driving the SDA line. If this transmitter is also a master device, it also must stop driving the SCL line. It then can monitor the lines for a Stop condition before trying to reissue its transmission. In the meantime, the other device that has not noticed any difference between the expected and actual levels on the SDA line continues with its original transmission. It can do so without any complications, because so far, the transmission appears exactly as expected with no other transmitter disturbing the message.

Slave Transmit mode can also be arbitrated, when a master addresses multiple slaves, but this is less common.

If two master devices are sending a message to two different slave devices at the address stage, the master sending the lower slave address always wins arbitration. When two master devices send messages to the same slave address, and addresses can sometimes refer to multiple slaves, the arbitration process must continue into the data stage.

Arbitration usually occurs very rarely, but it is a necessary process for proper multi-master support.

25.5.2 SLAVE RECEPTION

When the $\overline{R/W}$ bit of a matching received address byte is clear, the $\overline{R/W}$ bit of the SSP1STAT register is cleared. The received address is loaded into the SSP1BUF register and acknowledged.

When the overflow condition exists for a received address, then not Acknowledge is given. An overflow condition is defined as either bit BF of the SSP1STAT register is set, or bit SSP1OV of the SSP1CON1 register is set. The BOEN bit of the SSP1CON3 register modifies this operation. For more information see Register 25-4.

An MSSP1 interrupt is generated for each transferred data byte. Flag bit, SSP1IF, must be cleared by software.

When the SEN bit of the SSP1CON2 register is set, SCL will be held low (clock stretch) following each received byte. The clock must be released by setting the CKP bit of the SSP1CON1 register, except sometimes in 10-bit mode. See **Section 25.2.3 “SPI Master Mode”** for more detail.

25.5.2.1 7-bit Addressing Reception

This section describes a standard sequence of events for the MSSP1 module configured as an I²C Slave in 7-bit Addressing mode. All decisions made by hardware or software and their effect on reception. Figure 25-14 and Figure 25-15 is used as a visual reference for this description.

This is a step by step process of what typically must be done to accomplish I²C communication.

1. Start bit detected.
2. S bit of SSP1STAT is set; SSP1IF is set if interrupt on Start detect is enabled.
3. Matching address with $\overline{R/W}$ bit clear is received.
4. The slave pulls SDA low sending an \overline{ACK} to the master, and sets SSP1IF bit.
5. Software clears the SSP1IF bit.
6. Software reads received address from SSP1BUF clearing the BF flag.
7. If SEN = 1; Slave software sets CKP bit to release the SCL line.
8. The master clocks out a data byte.
9. Slave drives SDA low sending an \overline{ACK} to the master, and sets SSP1IF bit.
10. Software clears SSP1IF.
11. Software reads the received byte from SSP1BUF clearing BF.
12. Steps 8-12 are repeated for all received bytes from the master.
13. Master sends Stop condition, setting P bit of SSP1STAT, and the bus goes idle.

25.5.2.2 7-bit Reception with AHEN and DHEN

Slave device reception with AHEN and DHEN set operate the same as without these options with extra interrupts and clock stretching added after the 8th falling edge of SCL. These additional interrupts allow the slave software to decide whether it wants to ACK the receive address or data byte, rather than the hardware. This functionality adds support for PMBus™ that was not present on previous versions of this module.

This list describes the steps that need to be taken by slave software to use these options for I²C communication. Figure 25-16 displays a module using both address and data holding. Figure 25-17 includes the operation with the SEN bit of the SSP1CON2 register set.

1. S bit of SSP1STAT is set; SSP1IF is set if interrupt on Start detect is enabled.
2. Matching address with $\overline{R/W}$ bit clear is clocked in. SSP1IF is set and CKP cleared after the 8th falling edge of SCL.
3. Slave clears the SSP1IF.
4. Slave can look at the ACKTIM bit of the SSP1CON3 register to determine if the SSP1IF was after or before the \overline{ACK} .
5. Slave reads the address value from SSP1BUF, clearing the BF flag.
6. Slave sets \overline{ACK} value clocked out to the master by setting ACKDT.
7. Slave releases the clock by setting CKP.
8. SSP1IF is set after an \overline{ACK} , not after a NACK.
9. If SEN = 1 the slave hardware will stretch the clock after the \overline{ACK} .
10. Slave clears SSP1IF.

Note: SSP1IF is still set after the 9th falling edge of SCL even if there is no clock stretching and BF has been cleared. Only if NACK is sent to Master is SSP1IF not set

11. SSP1IF set and CKP cleared after 8th falling edge of SCL for a received data byte.
12. Slave looks at ACKTIM bit of SSP1CON3 to determine the source of the interrupt.
13. Slave reads the received data from SSP1BUF clearing BF.
14. Steps 7-14 are the same for each received data byte.
15. Communication is ended by either the slave sending an \overline{ACK} = 1, or the master sending a Stop condition. If a Stop is sent and Interrupt on Stop Detect is disabled, the slave will only know by polling the P bit of the SSTSTAT register.

FIGURE 25-15: I²C SLAVE, 7-BIT ADDRESS, RECEPTION (SEN = 1, AHEN = 0, DHEN = 0)

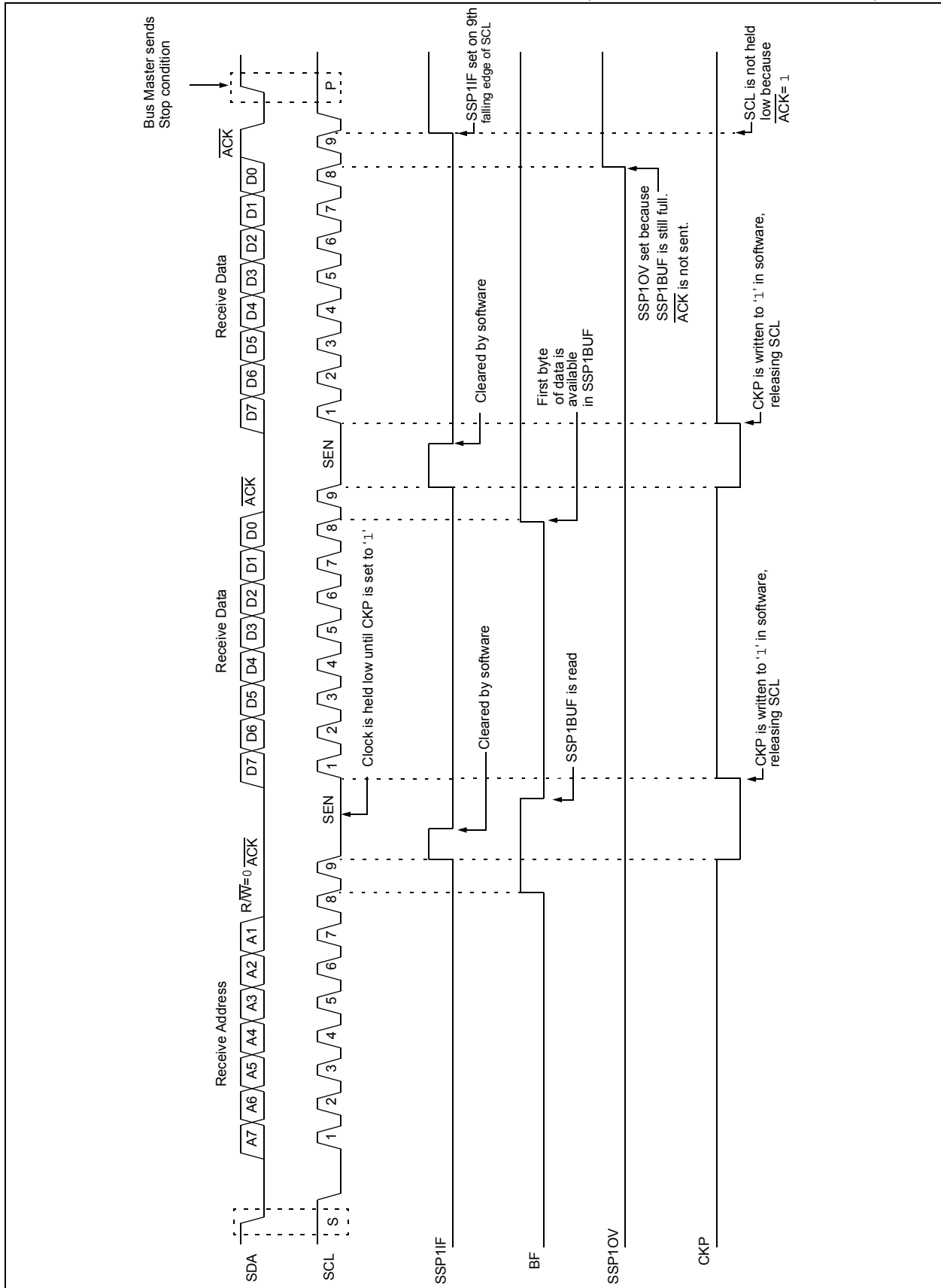
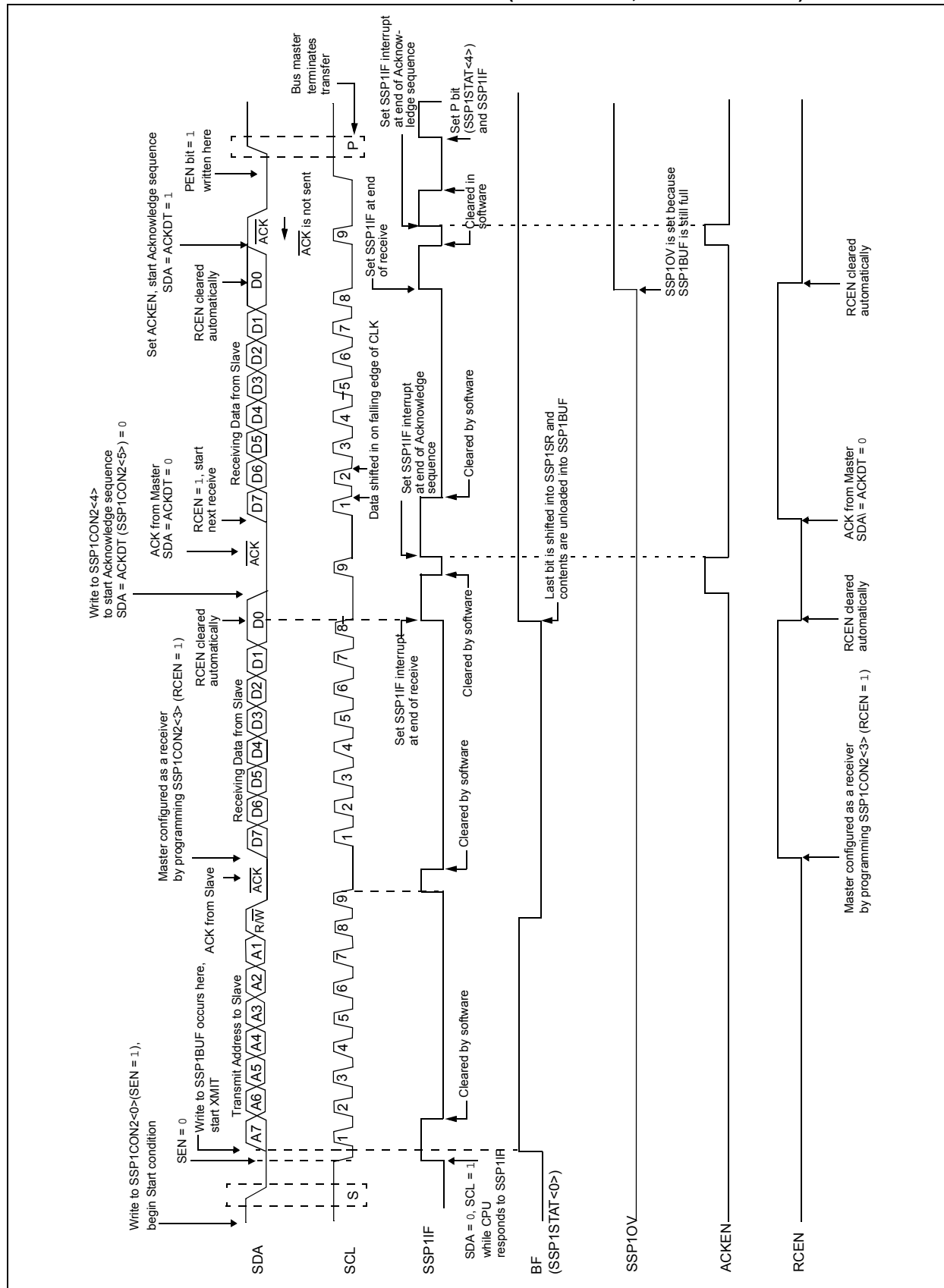


FIGURE 25-29: I²C MASTER MODE WAVEFORM (RECEPTION, 7-BIT ADDRESS)



25.6.8 ACKNOWLEDGE SEQUENCE TIMING

An Acknowledge sequence is enabled by setting the Acknowledge Sequence Enable bit, ACKEN bit of the SSP1CON2 register. When this bit is set, the SCL pin is pulled low and the contents of the Acknowledge data bit are presented on the SDA pin. If the user wishes to generate an Acknowledge, then the ACKDT bit should be cleared. If not, the user should set the ACKDT bit before starting an Acknowledge sequence. The Baud Rate Generator then counts for one rollover period (TBRG) and the SCL pin is deasserted (pulled high). When the SCL pin is sampled high (clock arbitration), the Baud Rate Generator counts for TBRG. The SCL pin is then pulled low. Following this, the ACKEN bit is automatically cleared, the Baud Rate Generator is turned off and the MSSP1 module then goes into Idle mode (Figure 25-30).

25.6.8.1 WCOL Status Flag

If the user writes the SSP1BUF when an Acknowledge sequence is in progress, then WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

25.6.9 STOP CONDITION TIMING

A Stop bit is asserted on the SDA pin at the end of a receive/transmit by setting the Stop Sequence Enable bit, PEN bit of the SSP1CON2 register. At the end of a receive/transmit, the SCL line is held low after the falling edge of the ninth clock. When the PEN bit is set, the master will assert the SDA line low. When the SDA line is sampled low, the Baud Rate Generator is reloaded and counts down to '0'. When the Baud Rate Generator times out, the SCL pin will be brought high and one TBRG (Baud Rate Generator rollover count) later, the SDA pin will be deasserted. When the SDA pin is sampled high while SCL is high, the P bit of the SSP1STAT register is set. A TBRG later, the PEN bit is cleared and the SSP1IF bit is set (Figure 25-31).

25.6.9.1 WCOL Status Flag

If the user writes the SSP1BUF when a Stop sequence is in progress, then the WCOL bit is set and the contents of the buffer are unchanged (the write does not occur).

FIGURE 25-30: ACKNOWLEDGE SEQUENCE WAVEFORM

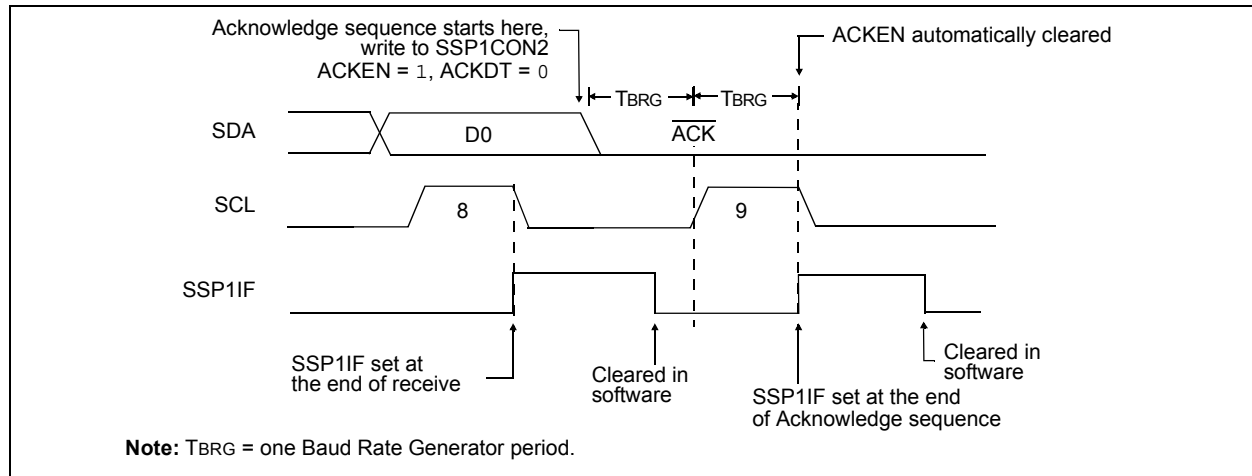
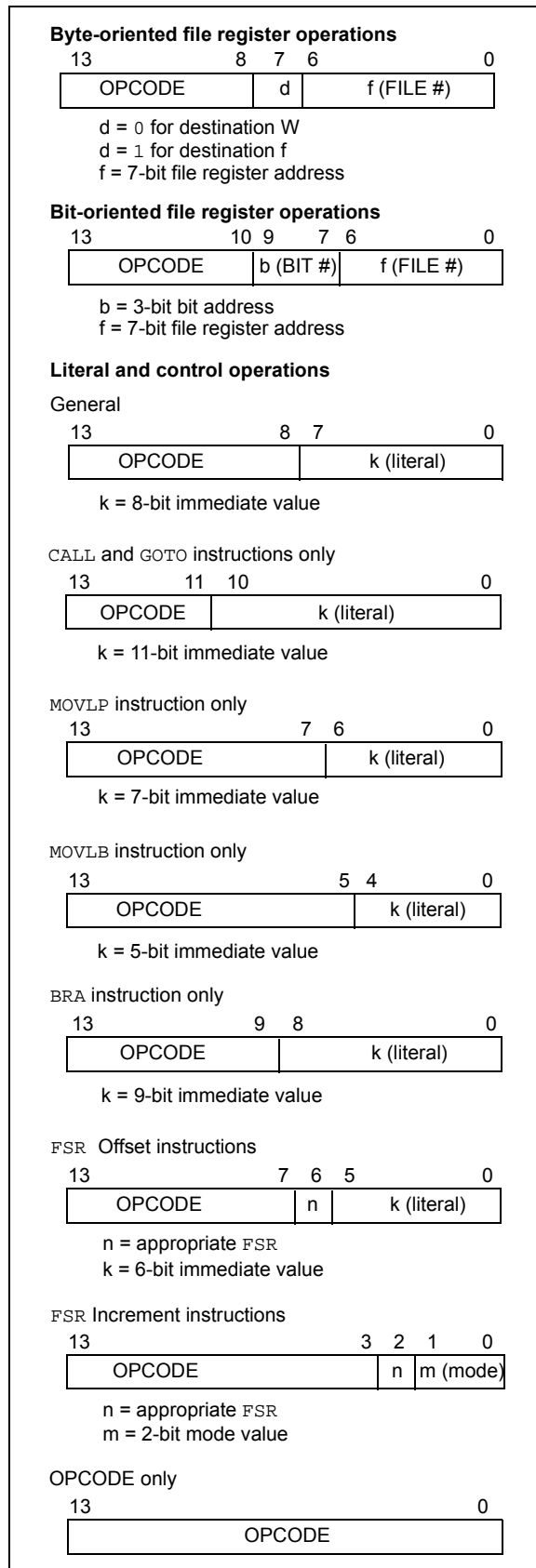


FIGURE 29-1: GENERAL FORMAT FOR INSTRUCTIONS



30.3 DC Characteristics: Power-Down Base Current (IPD) (Continued)

PIC12LF1840		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended						
PIC12F1840		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended						
Param No.	Device Characteristics	Min.	Typ†	Max. +85°C	Max. +125°C	Units	Conditions	
							VDD	Note
D026A*	Power-down Base Current (IPD) ⁽²⁾							
		—	250	—	—	μA	1.8	ADC Current (Note 1, 3)
		—	250	—	—	μA	3.0	Conversion in progress
D026A*		—	280	—	—	μA	2.3	ADC Current
		—	280	—	—	μA	3.0	Conversion in progress
		—	280	—	—	μA	5.0	VREGPM = 1 (Note 1, 3)
D027		—	3	12	15	μA	1.8	Cap Sense, Low Power
		—	4	15	18	μA	3.0	CPSRM = 0, CPSRNG = 01 (Note 1)
D027		—	6.3	13	16	μA	2.3	Cap Sense, Low Power
		—	8.5	18	20	μA	3.0	CPSRM = 0, CPSRNG = 01
		—	12.8	23	25	μA	5.0	VREGPM = 1 (Note 1)
D027A		—	6.0	15	20	μA	1.8	Cap Sense, Medium Power
		—	8.0	18	25	μA	3.0	CPSRM = 0, CPSRNG = 10 (Note 1)
D027A		—	9.5	20	25	μA	2.3	Cap Sense, Medium Power
		—	13	28	30	μA	3.0	CPSRM = 0, CPSRNG = 10
		—	17	32	35	μA	5.0	VREGPM = 1 (Note 1)
D027B		—	15	35	40	μA	1.8	Cap Sense, High Power
		—	39	60	75	μA	3.0	CPSRM = 0, CPSRNG = 11 (Note 1)
D027B		—	20	40	45	μA	2.3	Cap Sense, High Power
		—	42	68	80	μA	3.0	CPSRM = 0, CPSRNG = 11
		—	49	72	86	μA	5.0	VREGPM = 1 (Note 1)
D028		—	4.8	15	20	μA	1.8	Comparator,
		—	4.9	17	23	μA	3.0	Low Power, CxSP = 0 (Note 1)
D028		—	4.9	16	21	μA	2.3	Comparator,
		—	5.0	17	23	μA	3.0	Low Power, CxSP = 0
		—	5.2	18	24	μA	5.0	VREGPM = 1 (Note 1)
D028A		—	27	50	60	μA	1.8	Comparator,
		—	28	55	70	μA	3.0	Normal Power, CxSP = 1 (Note 1)
D028A		—	27	52	62	μA	2.3	Comparator,
		—	28	55	65	μA	3.0	Normal Power, CxSP = 1
		—	29	57	75	μA	5.0	VREGPM = 1 (Note 1)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

- Note 1:** The peripheral current is the sum of the base IDD or IPD and the additional current consumed when this peripheral is enabled. The peripheral Δ current can be determined by subtracting the base IDD or IPD current from this limit. Max. values should be used when calculating total current consumption.
- 2:** The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to Vss.
- 3:** ADC clock source is FRC.

FIGURE 30-20: I²C™ BUS START/STOP BITS TIMING

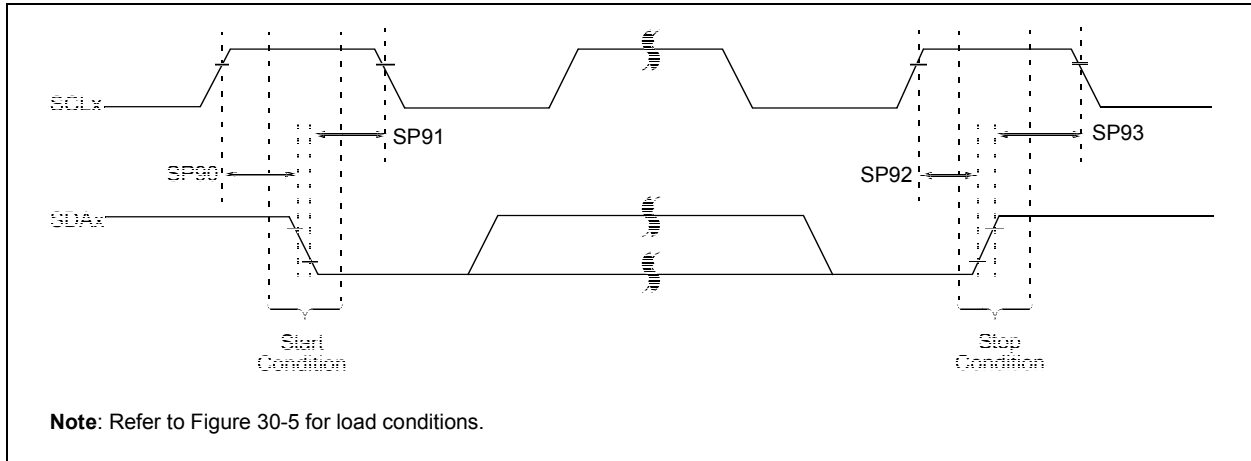


TABLE 30-15: I²C™ BUS START/STOP BITS REQUIREMENTS

Param. No.	Symbol	Characteristic		Min.	Typ.	Max.	Units	Conditions
SP90*	TSU:STA	Start condition	100 kHz mode	4700	—	—	ns	Only relevant for repeated Start condition
		Setup time	400 kHz mode	600	—	—		
SP91*	THD:STA	Start condition	100 kHz mode	4000	—	—	ns	After this period, the first clock pulse is generated
		Hold time	400 kHz mode	600	—	—		
SP92*	TSU:STO	Stop condition	100 kHz mode	4700	—	—	ns	
		Setup time	400 kHz mode	600	—	—		
SP93*	THD:STO	Stop condition	100 kHz mode	4000	—	—	ns	
		Hold time	400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

PIC12(L)F1840

FIGURE 31-37: I_{PD}, BROWN-OUT RESET (BOR), BORV = 1, PIC12LF1840 ONLY

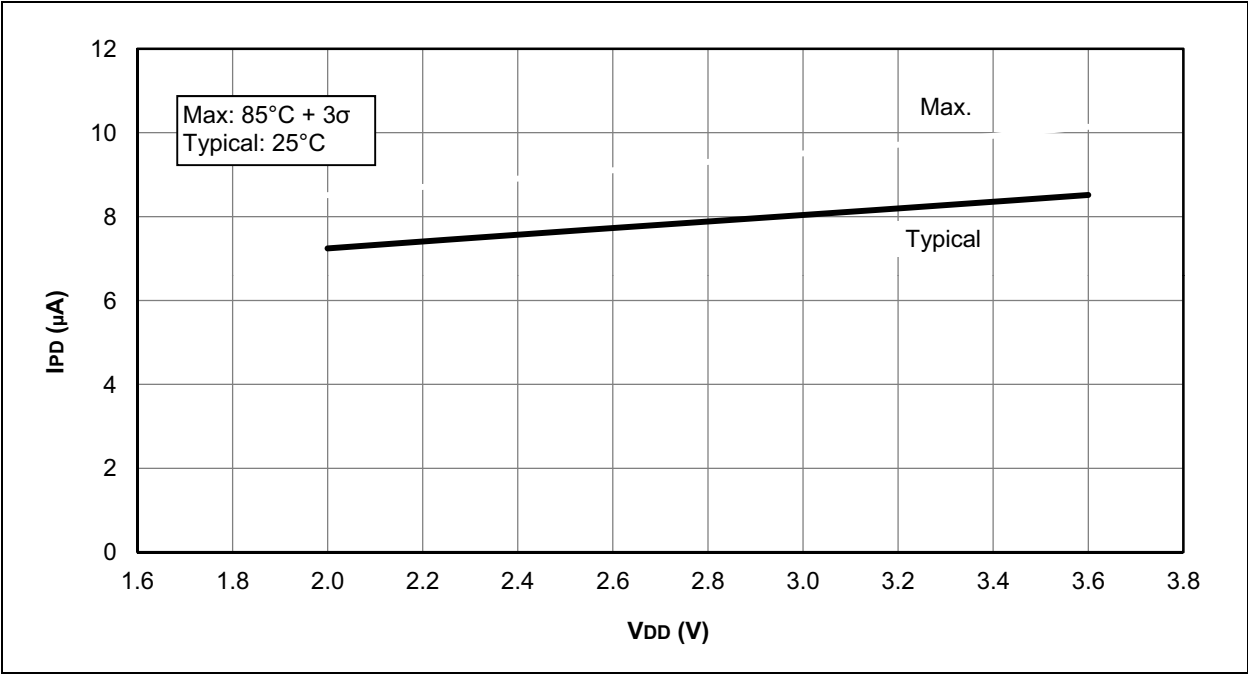
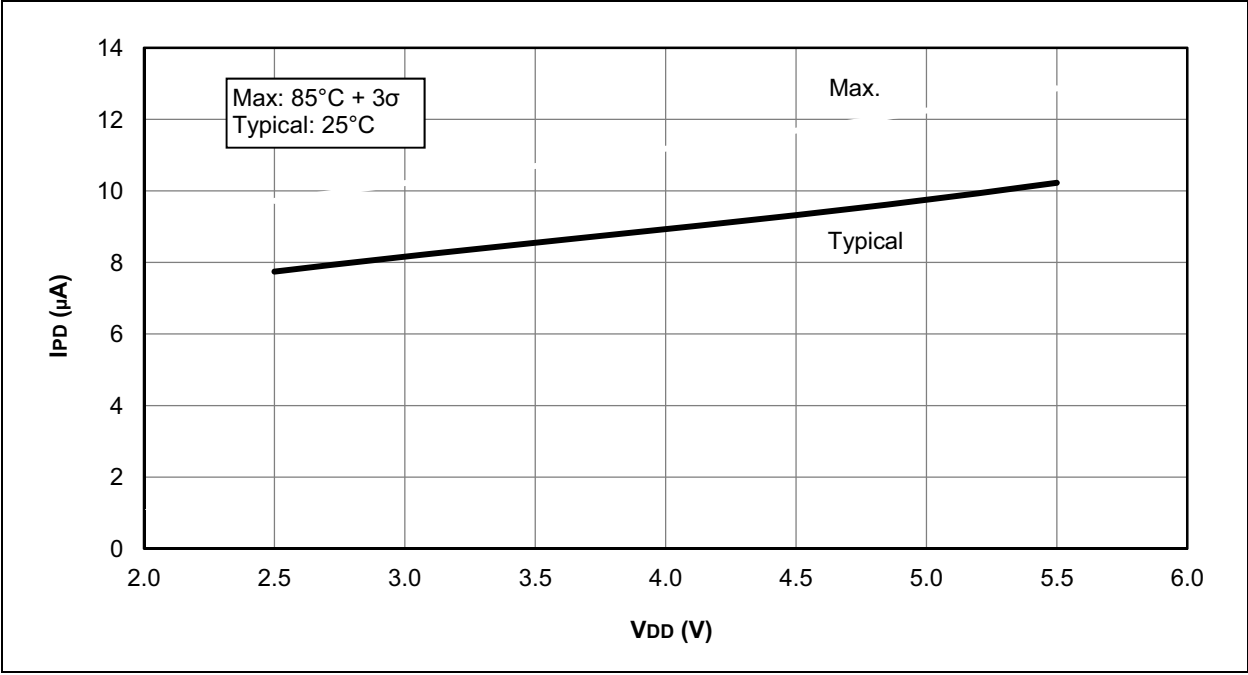


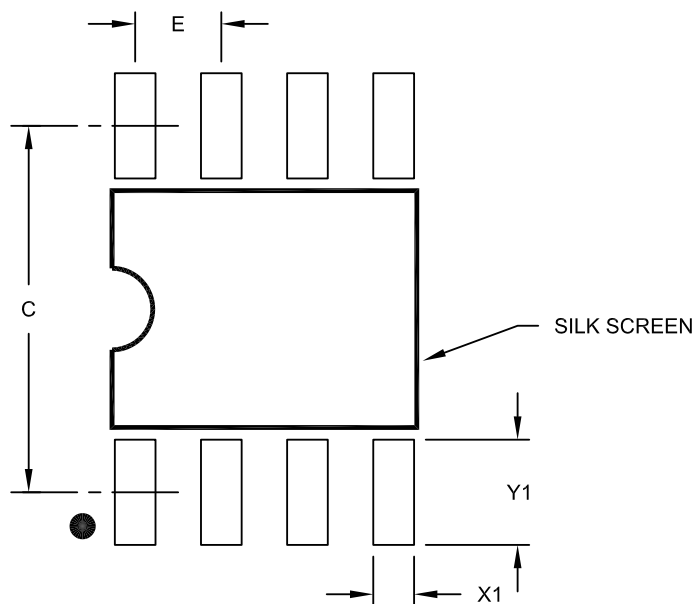
FIGURE 31-38: I_{PD}, BROWN-OUT RESET (BOR), BORV = 1, PIC12F1840 ONLY



PIC12(L)F1840

8-Lead Plastic Small Outline (SN) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

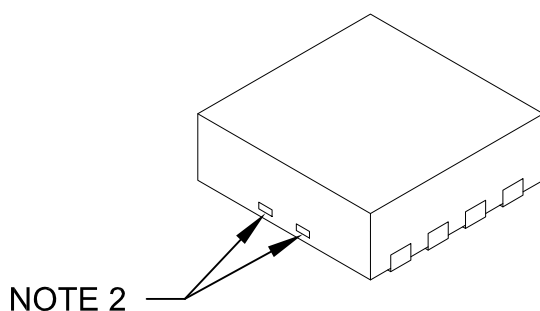
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

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PIC12(L)F1840

8-Lead Plastic Dual Flat, No Lead Package (MF) - 3x3x0.9mm Body [DFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Length	D	3.00 BSC		
Exposed Pad Width	E2	1.34	-	1.60
Overall Width	E	3.00 BSC		
Exposed Pad Length	D2	1.60	-	2.40
Contact Width	b	0.25	0.30	0.35
Contact Length	L	0.20	0.30	0.55
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars at ends.
3. Package is saw singulated
4. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-062C Sheet 2 of 2